
2025 H1 Operation Briefing of Nan Ya PCB Corp.

September 4th 2025



Disclaimer

The description of historical events might include the information that was not reviewed by accountants. Thus, it might be insufficient to fully exhibit the financial status or operation results of Nan Ya PCB Corp.

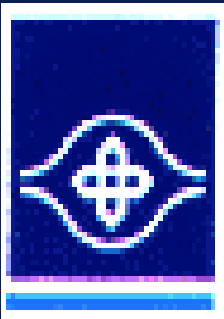
The actual operation results, financial status, and sales outlook in the future might be different from what will be indicated or implied in this meeting. The reasons may be including but not limited to the market demand, price fluctuation, competition dynamic, global economy, supply-chain, foreign exchange rate, and other risks that the Company cannot control.

Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



Agenda

- **Company Profile**
- **Financial Status**
- **Future Product Development**
- **Operational Strategies in 2025**



Company Profile

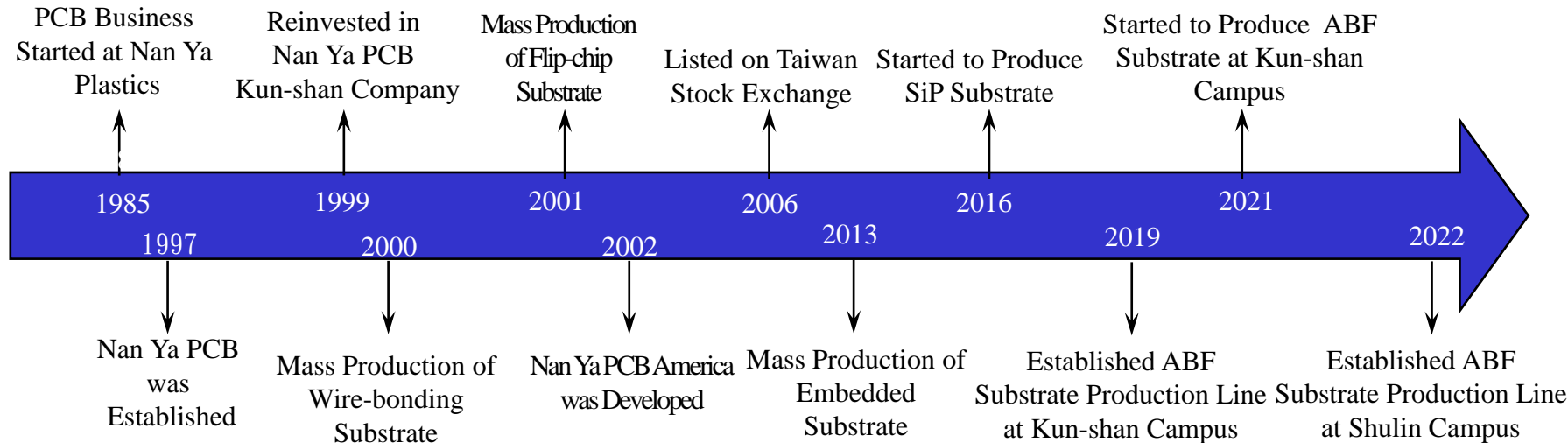
Business Overview

- **Subsidiary Company of Nan Ya Plastics Corp.**
- **Manufacture and Sell IC Substrates and PCBs**
- **2025 H1 Consolidated Revenues: NTD 18.0 Billion**
- **Market Value: NTD 72.4 Billion(June 30th 2025)**
- **Production Locations : Taiwan and China**



Company Profile

Milestone



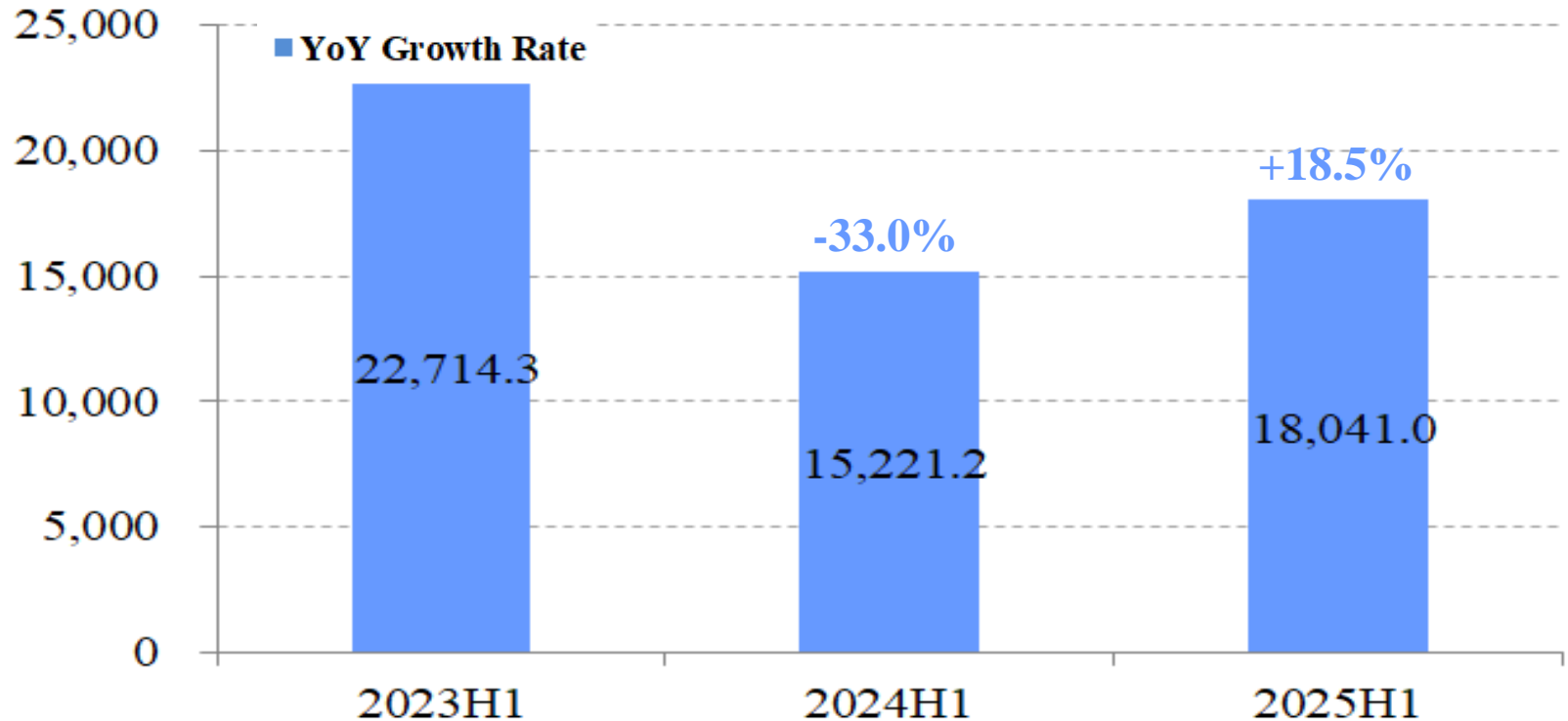
- 1985 : PCB business unit was formed at Nan Ya Plastics Corp. and started manufacturing PCBs
- 1997 : Approved by the Board of Nan Ya Plastics, Nan Ya PCB Corp. was established via reinvestment
- 1999 : Reinvested Nan Ya PCB Kun-shan Company with capital of USD29.8 million
- **2000 : Started manufacturing wire-bonding substrates**
- **2001 : Upgraded technologies and produced flip-chip substrates**
- 2002 : Established Nan Ya PCB America Corp.
- 2006 : Listed on Taiwan Stock Exchange with ticker 8046 TT
- 2013 : Upgraded technologies and produced Embedded substrates
- 2016 : Started to produce System in Package (SiP) substrates
- 2019 : In response to market demand, Nan Ya PCB Corp. started to build ABF substrate production line at Kun-shan Campus
- **2021 : Kun-shan Campus started to manufacture ABF substrates**
- **2022 : Shulin Campus started to manufacture ABF substrates**



Financial Status

Consolidated Revenues(IFRS) in Last 3 Years

NTD Million



- **Revenues in 2024 H1 were 33.0% lower than those in 2023H1:**

Due to ongoing inventory correction in telecom, revenues in 2024H1 were lower than those in the same period of 2023.

- **Revenues in 2025H1 were 18.5% greater than those in 2024H1:**

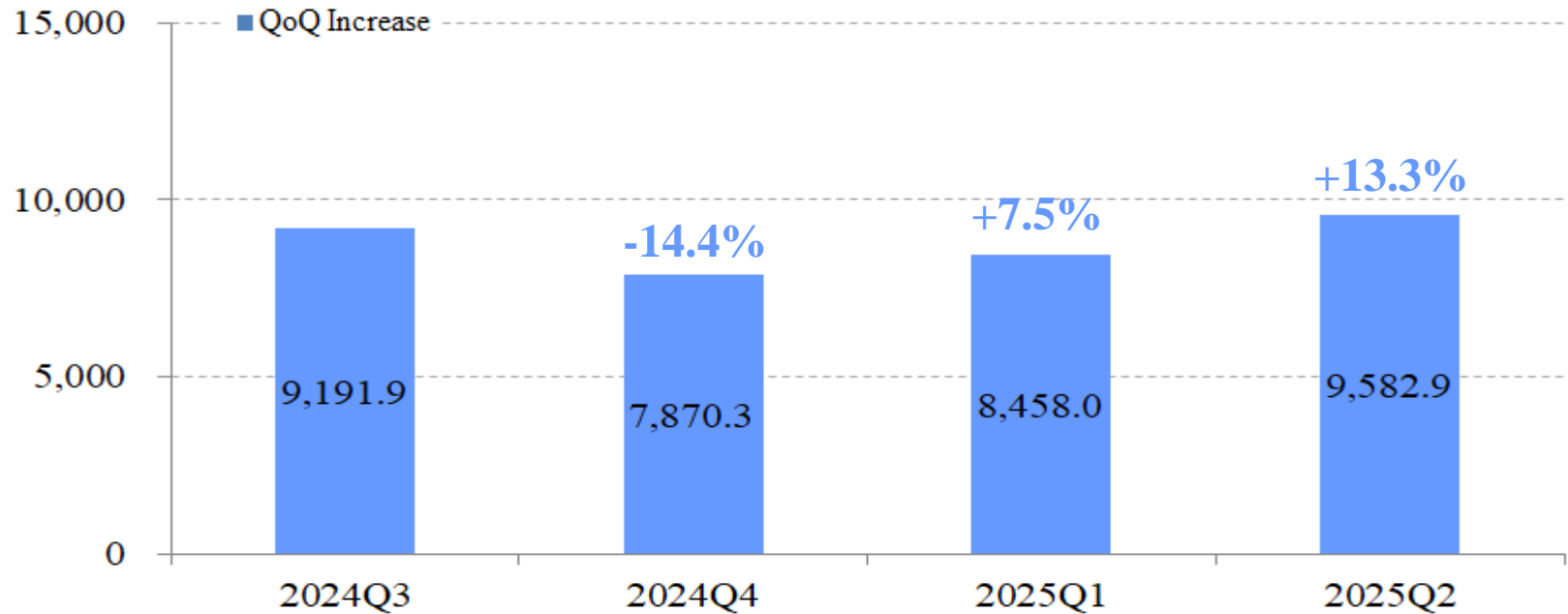
Increased demand for data center networking equipment upgrades and pre-stocking of consumer electronics led to higher revenue in 2025H1 compared to the same period in 2024.



Financial Status

Quarterly Consolidated Revenues(IFRS) in a Year

NTD Million



- **Revenues in 24Q4 were 14.4% lower than those in 24Q3:**

Due to the off-season for consumer electronics, and decreased demands in PCs and game consoles, revenue has decreased compared to 24Q4.

- **Revenues in 25Q1 were 7.5% greater than those in 24Q4:**

Increased demand for networking products from data centers led to revenue growth in 25Q1 compared to 24Q4.

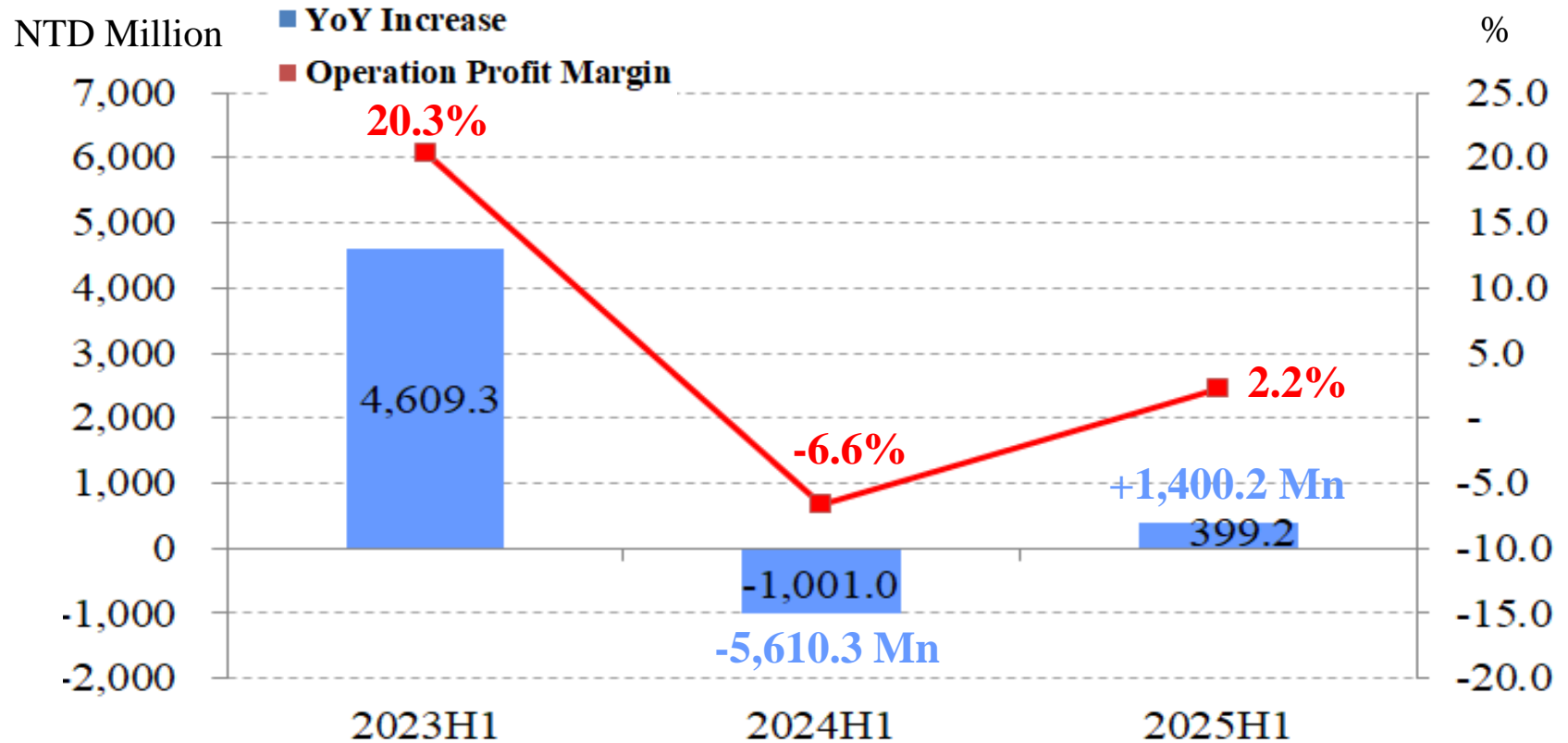
- **Revenues in 25Q2 were 13.3% greater than those in 25Q1:**

Stronger demand for cloud and edge computing products led to a 25Q2 revenue increase over 25Q1.



Financial Status

Operation Profits(Losses) in Last 3 Years

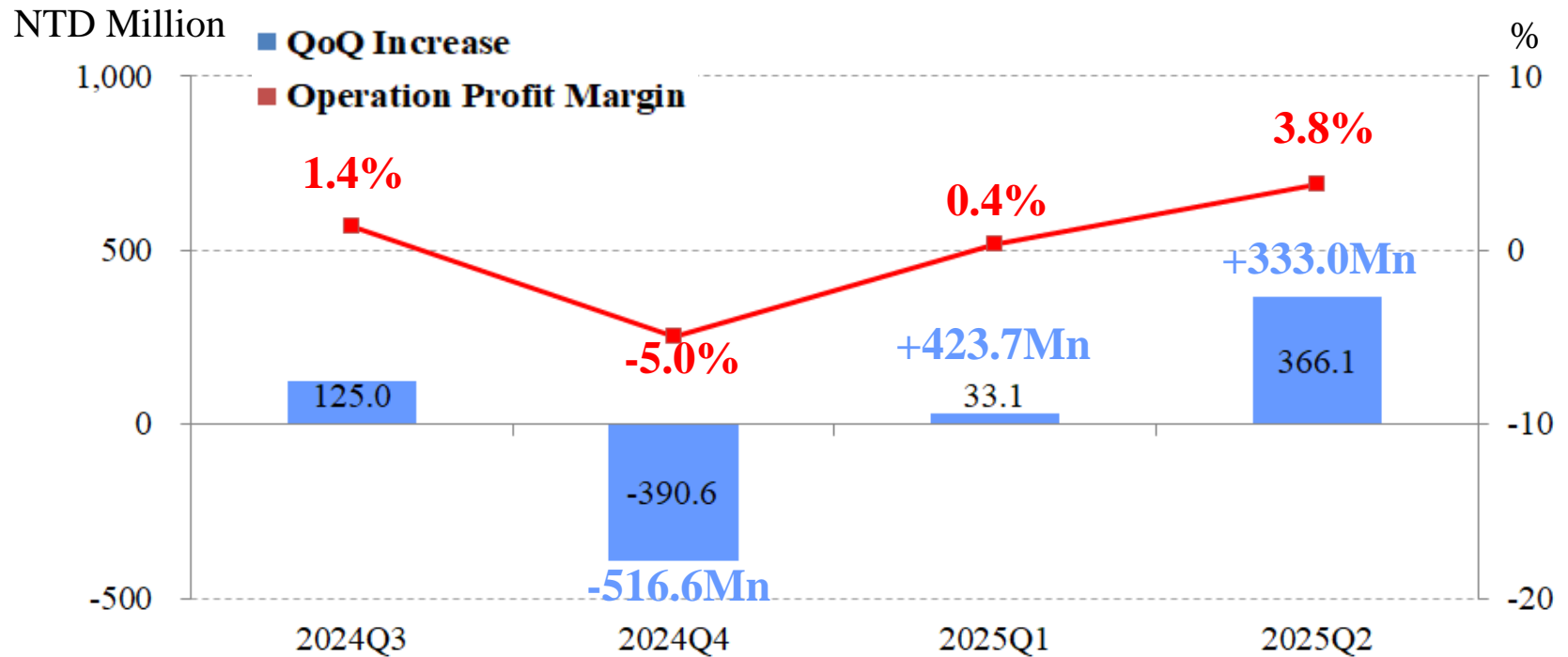


- **Operation profits in 2024H1 were decreasing NTD 5,610.3 Mn from 2023H1:**
Due to weak demand in telecom products, the operating profit decreased.
- **Operation profits in 2025H1 were increasing NTD 1,400.2 Mn from 2024H1:**
Operating profit increased due to the expanded revenue scale and a better product mix.



Financial Status

Quarterly Operation Profits in a Year

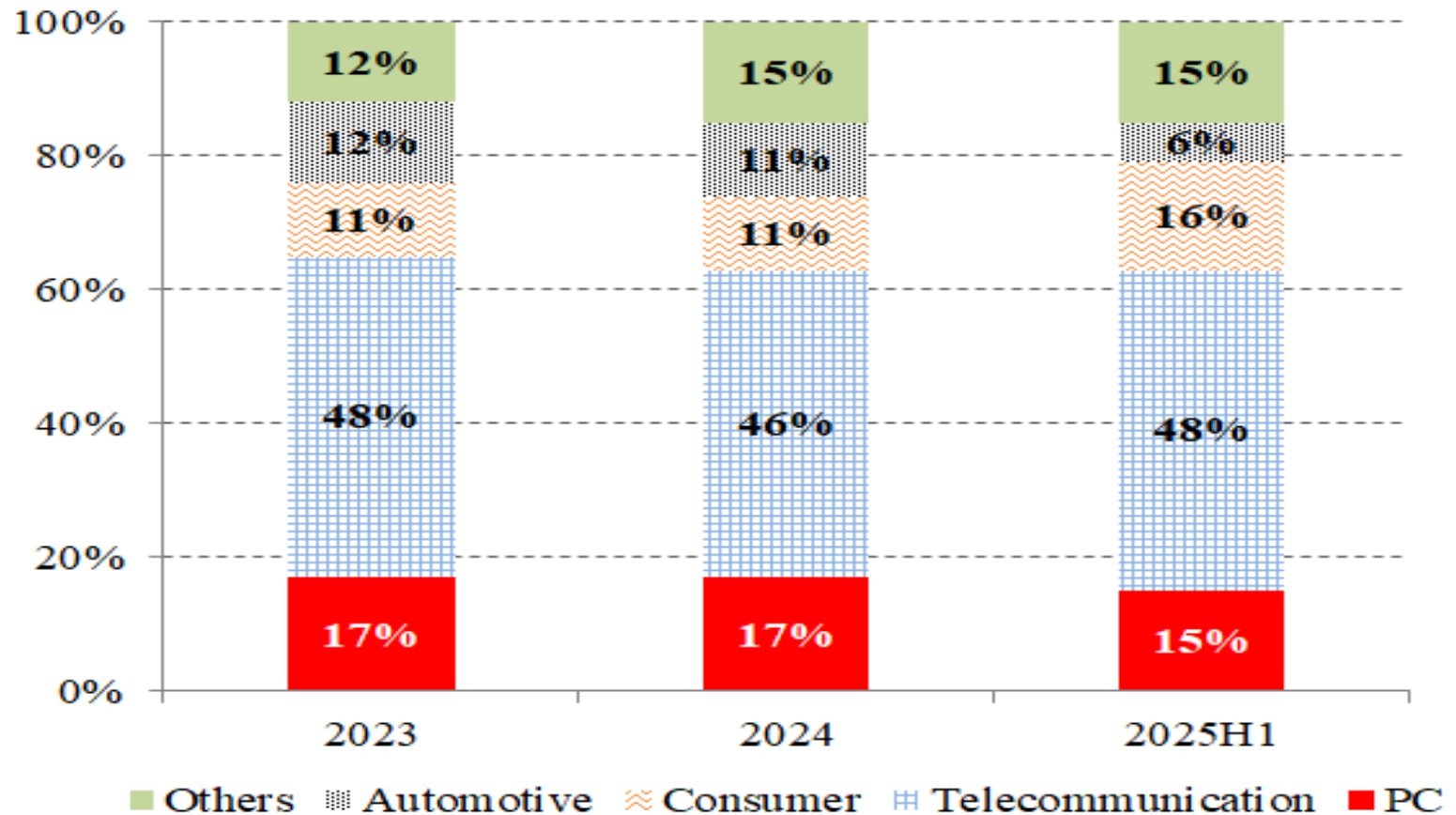


- **Operation profits in 24Q4 were decreasing NTD 516.6 Mn from 24Q3:**
Impacted by the off-season for consumer electronics, revenue has shrunk, and operating profit in the 24Q4 decreased compared to 24Q3.
- **Operation profits in 25Q1 were increasing NTD 423.7 Mn from 24Q4:**
Increased sales of high-end networking products led to higher operating profit in 25Q1 compared to 24Q4.
- **Operation profits in 25Q2 were increasing NTD 333.0 Mn from 25Q1:**
Demand for high-end cloud and edge computing applications increased, further boosting 25Q2 operating profit..



Financial Status

Revenue Structure(By Applications)

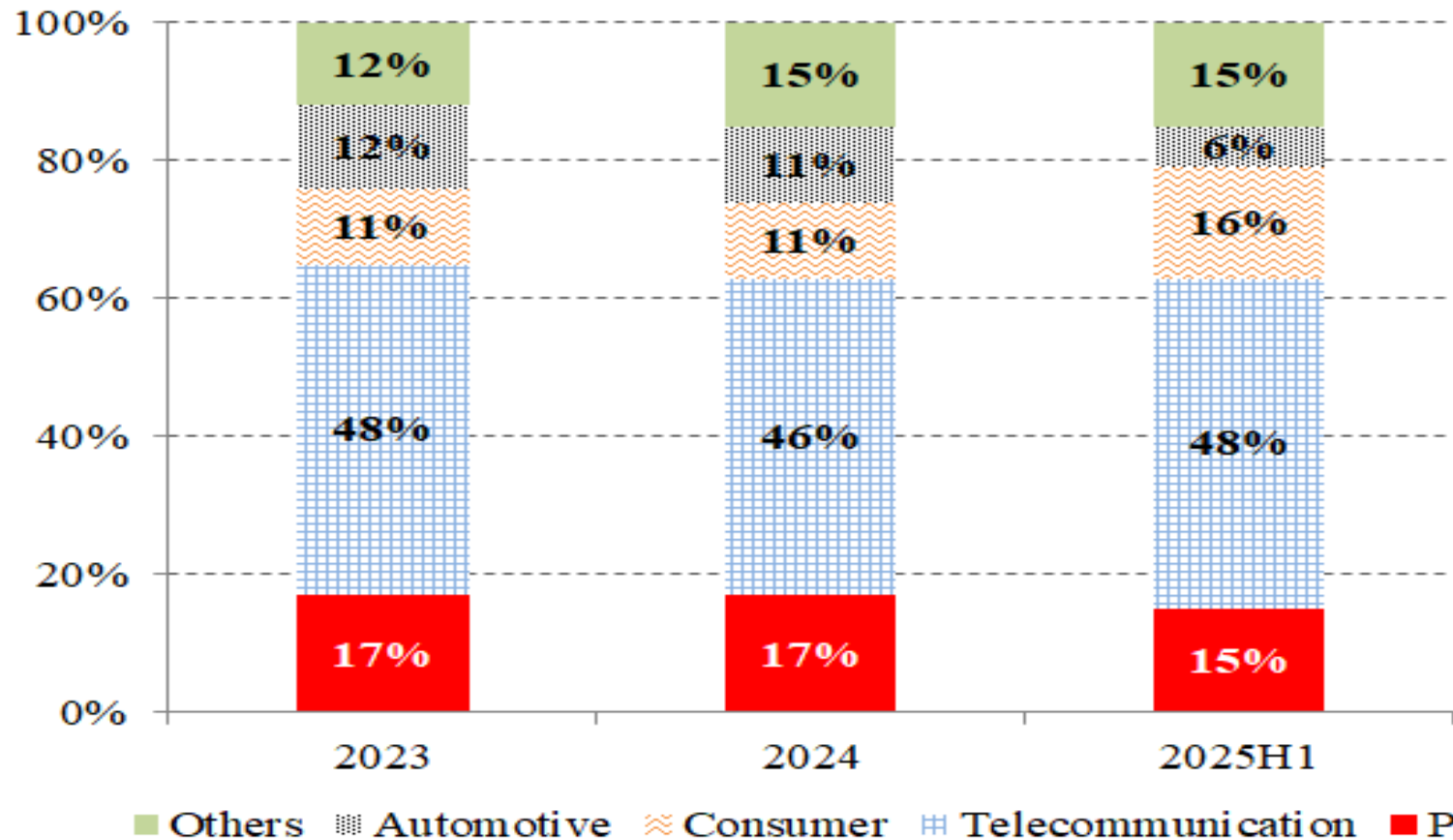


- The PC segment was affected by the traditional off-season for sales, resulting in a lower revenue contribution in 2025H1.
- Benefiting from data center networking equipment upgrades, demand for high-end switches increased, leading to a higher proportion of networking revenue in 2025H1.



Financial Status

Revenue Structure(By Applications)



- Consumer electronics customers accelerated inventory stocking to mitigate the risk of increased tariffs, resulting in higher related revenue in 2025H1.
- Intense price competition in the automotive sector, along with supply chain disruptions, has resulted in a decrease in revenue contribution in 2025H1.
- AI and HPC demands have been stable, leading to a flattish revenue ratio in 2025H1.



Future Product Development

Continue to Expand High Value Products

■ ABF Substrate

We will work closely with customers to develop substrates for products such as AI switches, AI routers, AI server processors, transceiver module chips, wireless network chips, 5nm ADAS processors, intelligent cockpits, high-end handheld game console processors, and TV chips, thereby strengthening our product mix.

■ BT Substrate

Our company will develop system-in-package (SiP) substrates for next-generation mobile device motherboards and camera sensors. We will also pursue networking business opportunities across various applications, including 5G antenna modules, 5G optical communication transceiver modules, and LEO satellite receiver application substrates. Additionally, we will mass produce automotive processor and programmable logic chip substrates.

■ Conventional PCB

Data center servers are driving the demand for HDI and multi-layer boards. Our company will develop and mass PCBs for AI server display cards and next-generation server network communication cards. Furthermore, to capitalize on opportunities in various edge AI products, we will also mass produce high-end PC and automotive millimeter-wave radar application PCBs, diversifying our product offerings.



Operational Strategies in 2025

Implementing 4 Major Transformations

- **Product Transformation:** Increase the proportion of high-value and differentiated products, and expand into new applications and markets..
- **Business Transformation:** Develop new materials, technologies, and products to strengthen the Company's capabilities.
- **Digital Transformation:** Leverage digital technologies to enhance AI and digital transformation, achieving intelligent operations.
- **Low-Carbon Transformation:** Expand the use of green energy, commit to energy conservation and carbon reduction, and implement the promotion of a circular economy.



Thank You

